

PRODUCT ADVANTAGE

- High Reliability
- Minimize Induced Stresses
- Enhance Mechanical Resistance
- Fast Flow
- Fast Low Temperature Cure
- Room Temperature Underfilling

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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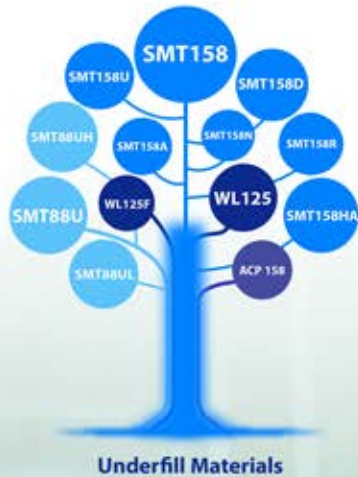
INNOVATION AT ITS BEST



UNDERFILL
MATERIALS

*Preferred by global leaders in the
electronics manufacturing industry*

YINCAE® Underfill Materials Family



Featured Underfills

SMT 88U: super-fast flow and fast low temperature (88°C) cure capillary underfill

SMT 158D: highly conductive (> 5 W/mK) diamond filled capillary underfill

SMT 158F: no resin bleeding, fast flow and fast cure capillary underfill

SMT 158HA: fast flow and low temperature slow cure high purity liquid epoxy underfill

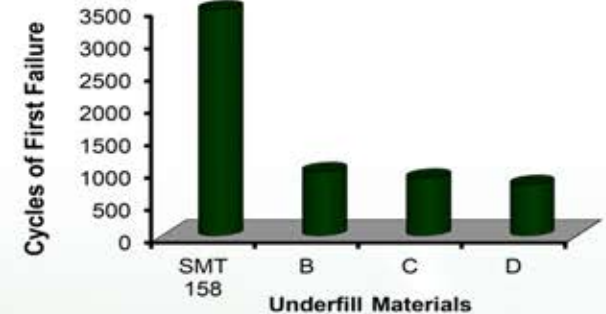
SMT 158N: non-flow, high purity liquid epoxy designed to replace corner and edge bonding adhesives

YINCAE® Underfill Materials are a set of capillary underfills, room temperature underfills, and wafer level underfills.

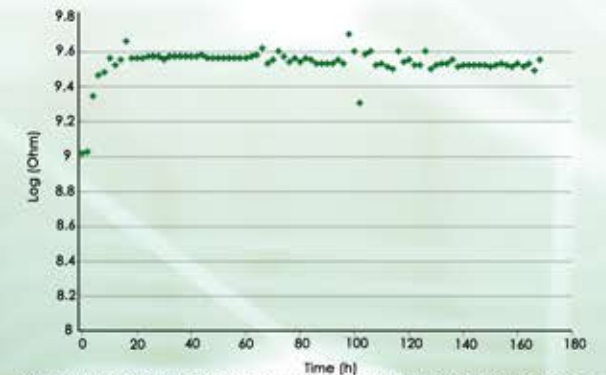
The SMT 158 capillary underfill series is a collection of capillary flow nano underfill. The products in this series offer rapid curing, fast flow, and can be used for CSP, BGA, PoP, LGA, and flip chip applications.

The SMT 88 series is a collection of underfill materials offering room temperature underfilling, super-fast flow, and super-fast low temperature cure.

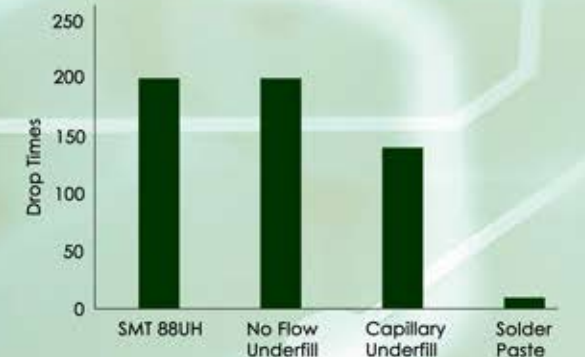
Product	Product Application	Curing Temp. (°C)
SMT 158	Capillary underfill	120-165
SMT 158U	Fast flow capillary underfill	120-165
SMT 158D	Conductive diamond filled capillary underfill	120-165
SMT 158A	Conductive capillary underfill	120-165
SMT 158N	Non-flow capillary underfill	120-165
SMT 158R	Filled fluxing capillary underfill	220-260
SMT 158H	Slow cure capillary underfill	120-165
SMT 158HA	Low temperature slow cure, no anhydrides	120-165
SMT 88UH	Fast, room temperature flow capillary underfill	120-165
SMT 88U	Fast, room temperature flow capillary underfill	88-110
SMT 88UL	Fast, room temperature flow capillary underfill	120-150
WL 125	Wafer level underfill	120-150
WL 125F	Wafer level underfill	120-150
ACP-158	Anisotropic, conductive underfill	120-165



SMT 158 shows thermocycling improvement over competitors underfills (Thermocycling conditions: -65°C - 150°C, 1h/cycle)



SMT 158 products have proven to resist failure from temperature and humidity changes (SIR Test: 85°C/85% RH)



SMT 88UH shows a high number for drops before failure (Drop height: 6 ft, concrete floor)